

P-Channel Enhancement Mode Power MOSFET

Description

- load switch
- battery protection applications

Features

- V_{DS}=-30V
- I_D=-60A
- $R_{DS(ON)}@V_{GS}=-10V$, TYP 6.6 m Ω
- $R_{DS(ON)}$ @ V_{GS} =-4.5V, $TYP8.5 m\Omega$

Absolute Maximum Ratings

Parameter		Symbol	Ratings	Units
Drain-Source Voltage		V_{DSS}	-30	V
Gate-Source Voltage		V_{GSS}	±20	V
Drain Current(Continuous) *AC	T _C =25°C	,	-60	А
	T _C =100°C	l _D	-33	A
Drain Current(Pulsed) *B		I _{DM}	-145	Α
Power Dissipation	T _C =25°C P _D 96		W	
Operating temperature / storage temperature		T _J /T _{STG}	-55~150	$^{\circ}\!\mathbb{C}$

Note:

- A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design.
- B. Repetitive rating, pulse width limited by junction temperature.
- C. The current rating is based on the t≤ 10s junction to ambient thermal resistance rating

Thermal Resistance Ratings

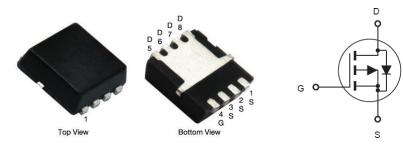
Parameter		Symbol	Typical	Maximum	Units
Maximum Junction-to-Ambient	Steady State	R _{thJC}	1	1.3	°C/W



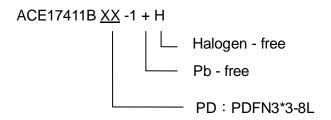
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Packaging Type

PDFN3*3-8L



Ordering information





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Electrical Characteristics

T_A=25°C, unless otherwise specified

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit			
Static									
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_{D} = -50 \mu A$	-30			V			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -3, V_{GS} = 0V$				μΑ			
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, $I_{DS} = -250 \mu A$	-1	-1.4		V			
Gate Leakage Current	I_{GSS}	V_{GS} =±20V, V_{DS} =0V			±100	nA			
Drain-Source On-state Resistance	R _{DS(on)}	$V_{GS} = -10V, I_{D} = -15A$		6.6	8.5	mΩ			
		$V_{GS} = -4.5V, I_{D} = -10A$		8.5	11				
Forward Transconductance	gFS	V_{DS} = -5V, I_{D} = -10A	-20			S			
Diode Forward Voltage	V_{SD}	I_{SD} = -1A , V_{GS} =0V			-1.2	V			
Diode Forward Current *AB	I _S	T _C =25°C			-32	Α			
Switching									
Total Gate Charge	Q_g	\/ 40\/ L 45A		93					
Gate-Source Charge	Q_{gs}	V_{GS} =-10V , I_{D} =-1.5A V_{DS} =-15V.		7.2		nC			
Gate-Drain Charge	Q_{gd}	V _{DS} =-13 V,		18.8					
Turn-on Delay Time	$t_{d(on)}$			24.5					
Turn-on Rise Time	t _r	V_{GS} =-10V, V_{DS} =-15V,		15		ns			
Turn-off Delay Time	t _{d(off)}	$R_L=30\Omega$, $R_G=6\Omega$		236					
Turn-Off Fall Time	t _f			96					
Dynamic									
Input Capacitance	C _{iss}	\/ 15\/\/ 0\/		4586		pF			
Output Capacitance	C _{oss}	V _{DS} =-15V,V _{GS} =0V, f=200kHz		448					
Reverse Transfer Capacitance	C _{rss}	I=ZUUK∏Z		406					

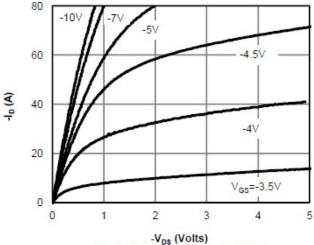
A: The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design.

B: The current rating is based on the t≤ 10s junction to ambient thermal resistance rating. Package limited42A ∘



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Typical Performance Characteristics (TJ = 25 °C, unless otherwise noted)



-V_{DS} (Volts) Fig 1: On-Region Characteristics

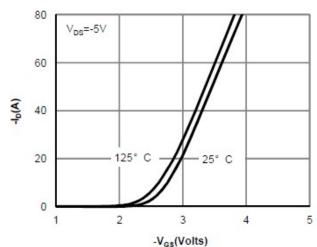
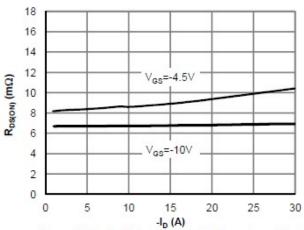


Figure 2: Transfer Characteristics



 $\mbox{-I}_{\rm D}\left(\mbox{A}\right)$ Figure 3: On-Resistance vs. Drain Current and Gate Voltage

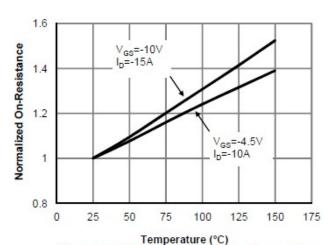


Figure 4: On-Resistance vs. Junction Temperature

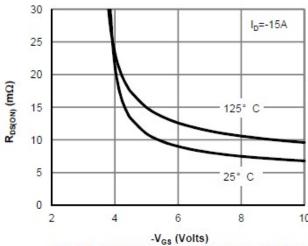
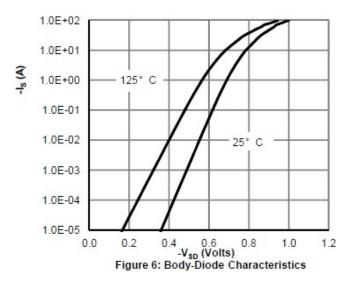


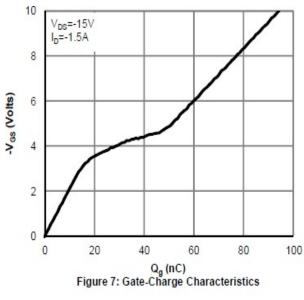
Figure 5: On-Resistance vs. Gate-Source Voltage

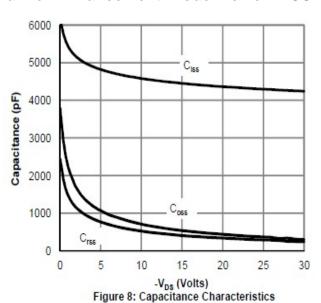


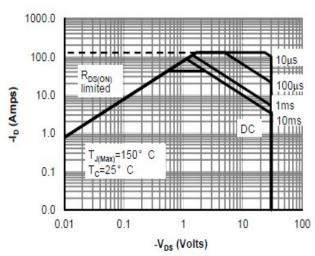
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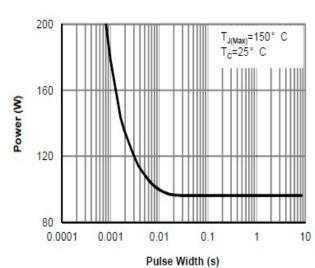


Figure 9: Maximum Forward Biased Safe Operating Area

Figure 10: Single Pulse Power Rating Junction-to-case

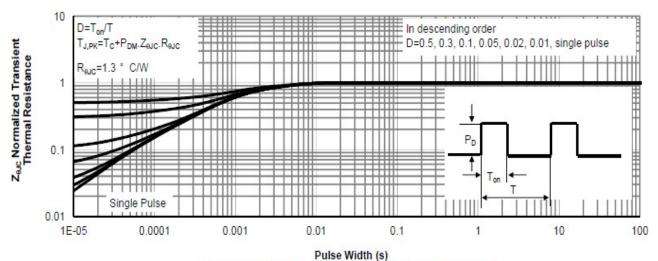


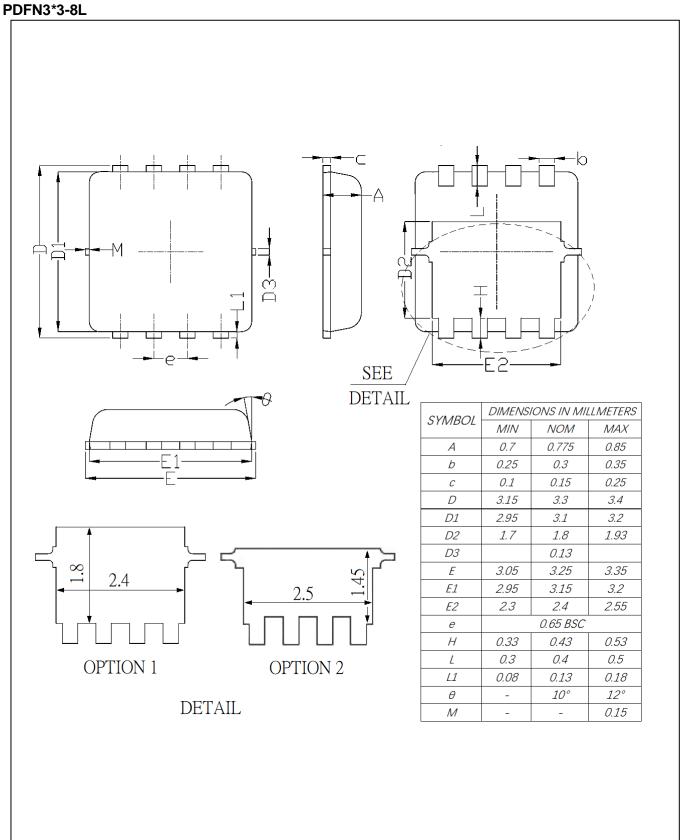
Figure 11: Normalized Maximum Transient Thermal Impedance

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Packing Information





ACE17411B P-Channel Enhancement Mode Power MOSFET

Notes

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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